

## CLAIM AMENDMENTS

1-14. (Cancelled)

15. (New) A pressure sensor comprising metallic terminals, a resin material molded integrally with said metallic terminals, and a semiconductor sensor and therefor a signal processing circuit placed in said resin material,

wherein an anaerobic adhesive is filled in gaps between said metallic terminals and said resin material after integrally molding said resin material with said metallic terminals.

16. (New) A pressure sensor according to Claim 15, wherein said anaerobic adhesive is a polymethacrylic adhesive.

17. (New) A pressure sensor according to Claim 15, wherein said semiconductor sensor and therefor said signal processing circuit are placed in an outer resin case, said outer resin case being molded integrally with metallic lead members for outputting a processed signal of said signal processing circuit, and the anaerobic adhesive is filled in gaps between said metallic lead members and said resin material after integrally molding said outer resin case with said metallic lead members.

18. (New) A pressure sensor comprising metallic terminals, a resin material molded integrally with said metallic terminals, and a semiconductor sensor and therefor a signal processing circuit placed in said resin material,

wherein a high-permeability adhesive is filled in gaps between said metallic terminals and said resin material after

integrally molding said resin material with said metallic terminals.

19. (New) A pressure sensor according to Claim 18, wherein said high-permeability adhesive is an acrylic adhesive.

20. (New) A pressure sensor according to Claim 18, wherein said semiconductor sensor and therefor said signal processing circuit are placed in an outer resin case, said outer resin case being molded integrally with metallic lead members for outputting a processed signal of said signal processing circuit, and the high-permeability adhesive is filled in gaps between said metallic lead members and said resin material after integrally molding said outer resin case with said metallic end members.

21. (New) An electronic component including metallic lead members partly serving as connector portion metallic terminals for electrical connection to an exterior, said electronic component being molded using a resin integrally with said metallic lead members,

wherein an anaerobic adhesive is filled in gaps generated due to curing shrinkage caused after said connector portion metallic terminals have been integral-molded with the resin.

22. (New) A method of manufacturing an electronic component, the method comprising the steps of:

(a) integral-molding metallic lead members with a resin, immersing an obtained electronic component in a tank of an anaerobic adhesive, and placing the electronic component in a vacuum state to purge out air bubbles remaining in gaps between

said metallic lead members and the resin, thereby filling the anaerobic adhesive in the gaps;

(b) taking out the electronic component molded using the resin integrally with the metallic lead members from the tank of the anaerobic adhesive after the anaerobic adhesive has been filled in the gaps, and leaving the electronic component to stand in the atmosphere, thereby hardening the anaerobic adhesive filled in the gaps; and

(c) cleaning the electronic component to remove the anaerobic adhesive from other areas than the gaps.

23. (New) An electronic component manufactured by a manufacturing method according to Claim 22, wherein even when degassing is not completely performed in the vacuum state and air bubbles remain in the gaps between said metallic lead members and the resin, the air bubbles are made immobile after hermetic sealing by the anaerobic adhesive and the hermetic sealing is ensured.

24. (New) A flowmeter comprising an electronic component molded using a resin integrally with metallic terminals partly serving as connector portion metallic terminals for electrical connection to the exterior,

wherein an anaerobic adhesive is filled in gaps generated due to curing shrinkage caused after said connector portion metallic terminals have been integral-molded with the resin.

25. (New) A flowmeter according to Claim 24, wherein said electronic component is molded using the resin integrally with metallic lead members for supporting a flow measuring device and

establishing electrical connection, and

wherein the anaerobic adhesive is filled in the gaps generated due to curing shrinkage caused after said metallic lead members have been integral molded with the resin.

26. (New) An electronic component according to Claim 21, wherein the anaerobic adhesive is filled in the gaps generated in said electronic component including the metallic lead members integral-molded with the resin, the anaerobic adhesive covering up to terminal end surfaces and resin end surfaces for sealing-off.

27. (New) A method of manufacturing an electronic component comprising a resin member and a metallic member, the method comprising the steps of:

insert-molding said metallic member in said resin member;  
immersing said resin member and said insert-molded metallic member in an anaerobic adhesive or a high-permeability adhesive;  
exposing said resin member and said insert-molded metallic member after the immersion to a first pressure lower than atmospheric pressure, and exposing both said members to a second pressure higher than the first pressure; and

pulling up said resin member and said insert-molded metallic member from the anaerobic adhesive or the high-permeability adhesive.

28. (New) An electronic component assembled, when used, in a sensor for detecting a physical variable in an automobile, said electronic component comprising:

a metallic member through which an electric signal flows;

and

a resin member molded with said metallic member inserted therein,

wherein air bubbles are enclosed in gaps between said resin member and said metallic member by an adhesive.

29. (New) An electronic component according to Claim 26, wherein said sensor is a flowmeter for detecting a fluid flow rate or a pressure sensor for detecting a fluid pressure, and

wherein said adhesive is an anaerobic adhesive or a high-permeability adhesive.

30. (New) An electronic component according to Claim 26, wherein said sensor is a flowmeter for detecting a fluid flow rate or a pressure sensor for detecting a fluid pressure, and

wherein said adhesive is a polymethacrylic or acrylic adhesive.